

### NCE N-Channel Enhancement Mode Power MOSFET

### **General Description**

The NCE7580 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

#### **Features**

- $V_{DS}$ =75V;  $I_D$ =80A@  $V_{GS}$ =10V;  $R_{DS(ON)}$ <8m $\Omega$  @  $V_{GS}$ =10V
- Special process technology for high ESD capability
- Special designed for convertors and power controls
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation

### **Application**

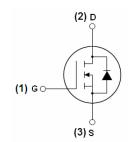
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

#### **Product Summary**

BV <sub>DSS</sub> typ.	84	٧
R <sub>DS(ON)</sub> typ.	6.5	mΩ
max.	8.0	mΩ
I <sub>D</sub>	80	Α

#### 100% UIS TESTED!





TO-220-3L top view

Schematic diagram

#### Package Marking and Ordering Information

	<u> </u>	<u> </u>			
Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE7580	7580	TO-220-3L	-	-	-

### Table 1. Absolute Maximum Ratings ( $T_c=25^{\circ}$ C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	75	V
Gate-Source Voltage (V <sub>DS</sub> =0V)	V <sub>GS</sub>	±25	V
Drain Current (DC) at Tc=25℃	I <sub>D (DC)</sub>	80	А
Drain Current (DC) at Tc=100°C	I <sub>D (DC)</sub>	60	А
Drain Current-Continuous@ Current-Pulsed (Note 1)	I <sub>DM (pluse)</sub>	320	А
Peak diode recovery voltage	dv/dt	30	V/ns
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	170	W
Derating factor		1.13	W/℃
Single pulse avalanche energy (Note 2)	E <sub>AS</sub>	580	mJ
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 175	$^{\circ}$

 $Notes\ 1. \\ \textit{Repetitive Rating: Pulse width limited by maximum junction temperature}$ 

2.EAS condition : Tj=25 $^{\circ}$ C,VDD=50V,VG=10V,L=0.3mH,ID=62A;



### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.88	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	63	°C/W

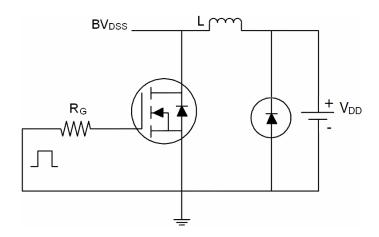
Table 3. Electrical Characteristics ( $T_C=25\,^{\circ}\mathrm{C}\,\mathrm{unless}$  otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	75	84		V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =75V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =75V,V <sub>GS</sub> =0V			10	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	2	2.85	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =40A		6.5	8	mΩ
Dynamic Characteristics						
Forward Transconductance	<b>9</b> FS	V <sub>DS</sub> =10V,I <sub>D</sub> =40A	20	-	-	S
Input Capacitance	C <sub>lss</sub>	\\ O5\\\\ 0\\		4400		PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V,		340		PF
Reverse Transfer Capacitance	C <sub>rss</sub>	- F=1.0MHz		260		PF
Total Gate Charge	Qg	V 20VI 20A		100		nC
Gate-Source Charge	Q <sub>gs</sub>	- V <sub>DS</sub> =30V,I <sub>D</sub> =30A,		20		nC
Gate-Drain Charge	$Q_{gd}$	- V <sub>GS</sub> =10V		30		nC
Switching times					•	•
Turn-on Delay Time	t <sub>d(on)</sub>			17.8		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =30 $V$ , $I_D$ =2 $A$ , $R_L$ =15 $\Omega$		11.8		nS
Turn-Off Delay Time	$t_{d(off)}$	$V_{GS}$ =10 $V$ , $R_{G}$ =2.5 $\Omega$		56		nS
Turn-Off Fall Time	t <sub>f</sub>			14.6		nS
Source- Drain Diode Characteristics		•				
Source-drain current(Body Diode)	I <sub>SD</sub>				80	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>				320	Α
Forward on voltage <sup>(Note 1)</sup>	V <sub>SD</sub>	Tj=25℃,I <sub>SD</sub> =40A,V <sub>GS</sub> =0V			1.2	V
Reverse Recovery Time <sup>(Note 1)</sup>	t <sub>rr</sub>	T:-05°0   -75   di/dt-400   / / / -			36	nS
Reverse Recovery Charge <sup>(Note 1)</sup>	Q <sub>rr</sub>	- Tj=25℃,I <sub>F</sub> =75A,di/dt=100A/μs			56	nC
Forward Turn-on Time	t <sub>on</sub>	Intrinsic turn-on time is negligible(turn-on is dominated by L <sub>S</sub> +				y L <sub>S</sub> +L <sub>D</sub> )
		•				

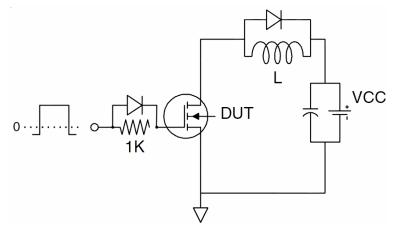
Notes 1.Pulse Test: Pulse Width ≤ 300 $\mu$ s, Duty Cycle ≤ 1.5%, R<sub>G</sub>=25 $\Omega$ , Starting Tj=25 $^{\circ}$ C

### **Test Circuit**

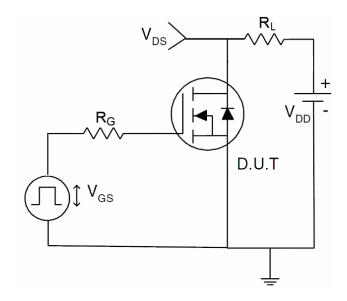
## 1) E<sub>AS</sub> Test Circuit



## 2) Gate Charge Test Circuit



### 3) Switch Time Test Circuit





### **Typical Electrical and Thermal Characteristics (curves)**

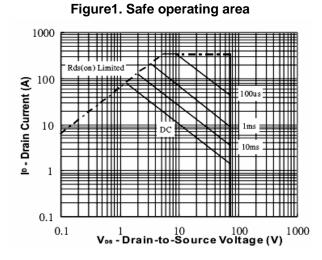


Figure 2. Source-Drain Diode Forward Voltage

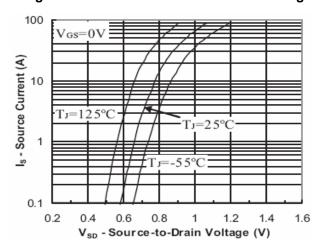


Figure 3. Output characteristics

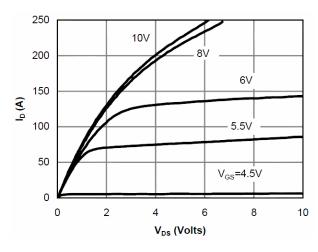


Figure 4. Transfer characteristics

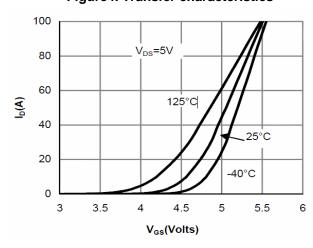


Figure 5. Static drain-source on resistance

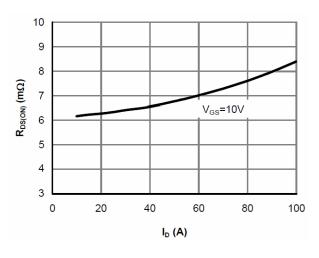
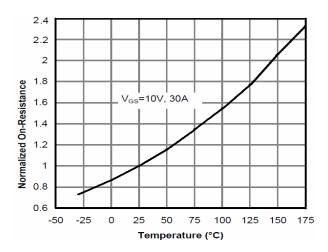


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature





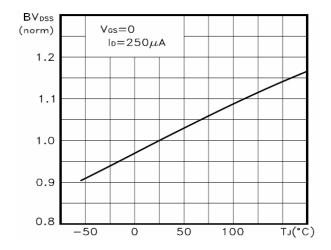
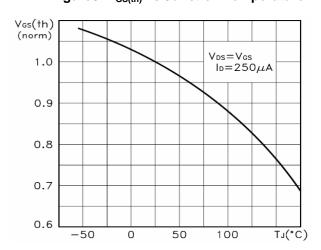
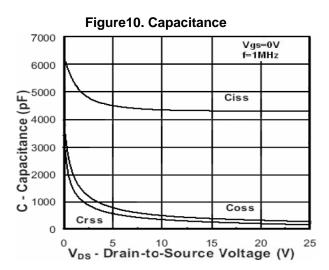


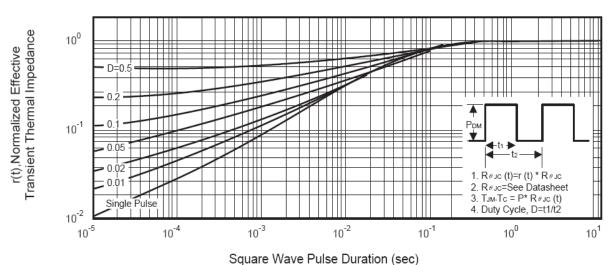
Figure 8. V<sub>GS(th)</sub> vs Junction Temperature



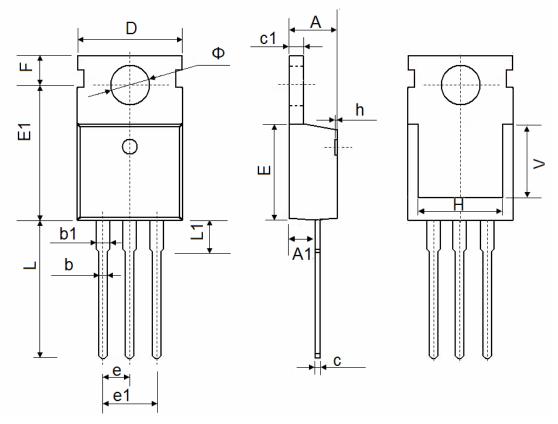
(STO) V<sub>DS</sub>=30V V<sub>DS</sub>=30V V<sub>DS</sub>=30A V<sub>DS</sub>=30A

Figure 9. Gate charge waveforms





# **TO-220-3L Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.54	2.540 TYP.		TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500 REF.		0.295 REF.		
Ф	3.400	3.800	0.134	0.150	

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